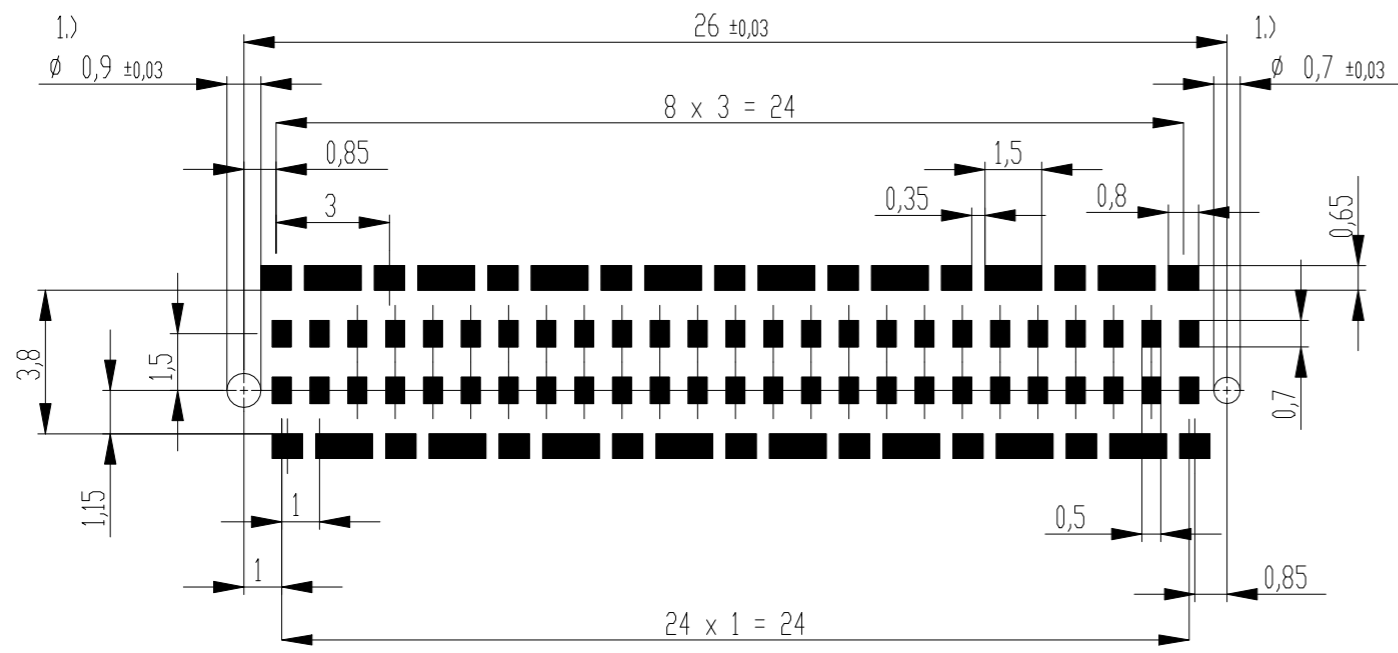
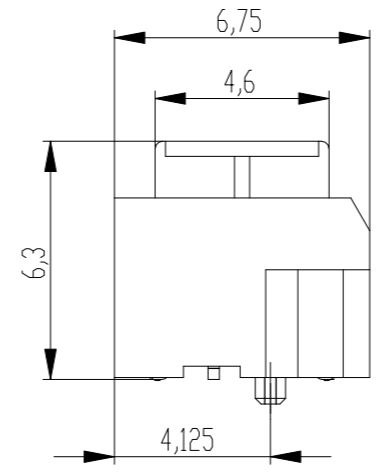


Leiterplatten-Layout Vorschlag / PCB-layout proposal

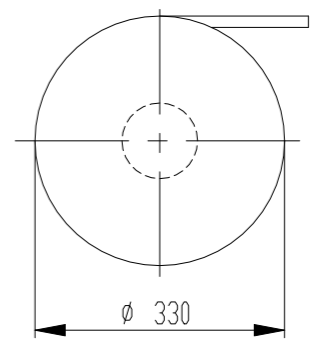


1.) Durchmesser des Bohrers / Drill tool

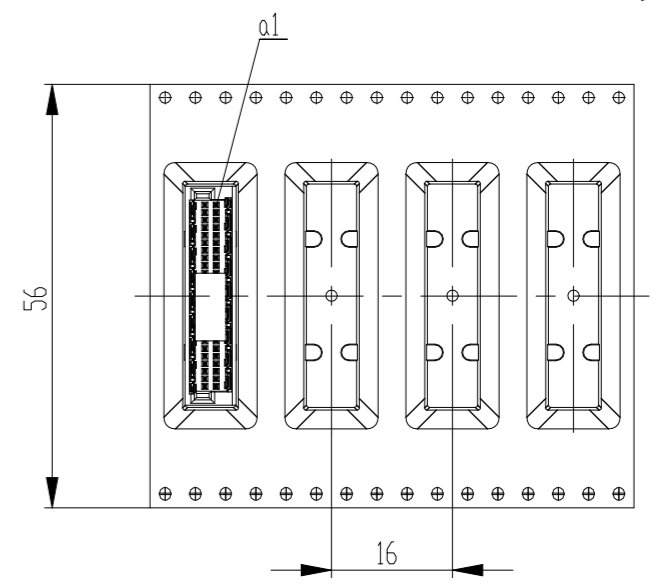
Für weitere Layout Details bitte Applikations Schrift MicroSpeed beachten.  
For further layout details please consider MicroSpeed application note.



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
tape on reel packaging according to DIN IEC 60286-3  
Verpackungseinheit: 400 Stück  
packaging unit: 400 pcs



Abspulrichtung - reel off direction



Anforderungsstufe 1  
performance level 1

Kontaktbereich vergoldet  
mating area gold plating

Anschlussbereich verzinkt 4-6 µm  
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
coplanarity area of termination ≤ 0,1 mm

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The German version of this drawing has been offered for convenience only  
and may deviate from the English original.  
In case of any deviation the English version shall prevail.

Dimension no.	Tolerances Dim. for Information ISO 8015	All Dimensions in mm	Scale 5:1 Material
Customer drawing: THIS DRAWING IS A CONTROLLED DOCUMENT.	Subject to modification without prior notice. Drawing will not be updated.		ERNI-Messerl. 1mm SMD 50pol. BM EMV Male 1mm SMD 50 cont. BM EMV
TE Connectivity		C-374723-E	I A3
e	28.01.2014	Class MSPEED	
Index	Date		